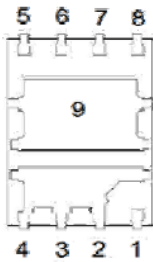
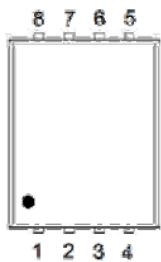


PK626HY

Dual N-Channel Enhancement Mode MOSFET

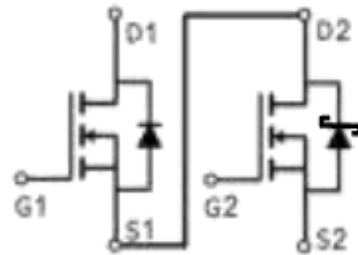
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D	CH.
30V	2.4m Ω @ $V_{GS} = 10V$	99A	Q2
30V	7m Ω @ $V_{GS} = 10V$	43A	Q1



1 : G1
2,3,4 : D1
5,6,7 : S2
8 : G2
9 : S1/D2

PDFN 5*6P



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	CH.	LIMITS	UNITS
Drain-Source Voltage		V _{DS}	Q2	30	V
			Q1	30	
Gate-Source Voltage		V _{GS}	Q2	±20	
			Q1	±20	
Continuous Drain Current ³	T _C = 25 °C	I _D	Q2	99	A
			Q1	43	
	T _C = 100 °C		Q2	63	
			Q1	27	
Pulsed Drain Current ¹		I _{DM}	Q2	120	
			Q1	55	
Continuous Drain Current	T _A = 25 °C	I _D	Q2	25	
			Q1	11	
	T _A = 70 °C		Q2	20	
			Q1	9.5	
Avalanche Current		I _{AS}	Q2	48	
			Q1	23	
Avalanche Energy	L = 0.1mH	E _{AS}	Q2	115	mJ
			Q1	26.4	
Power Dissipation	T _C = 25 °C	P _D	Q2	43	W
			Q1	24	
	T _C = 100 °C		Q2	17	
			Q1	9.6	

PK626HY

Dual N-Channel Enhancement Mode MOSFET

Power Dissipation	T _A = 25 °C	P _D	Q2	2.7	W
	T _A = 70 °C		Q1	1.7	
			Q2	1.7	
			Q1	1.1	
Operating Junction & Storage Temperature Range		T _J , T _{STG}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	CH.	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$	Q2		46	$^{\circ}\text{C} / \text{W}$
		Q1		70	
Junction-to-Case	$R_{\theta JC}$	Q2		2.9	
		Q1		5.2	

¹Pulse width limited by maximum junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design.

³Package limitation current :Q1=29A,Q2=34A.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	CH.	LIMITS			UNITS
				MIN	TYP	MAX	
STATIC							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	Q2	30			V
		$V_{GS} = 0V, I_D = 250\mu A$	Q1	30			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	Q2	1.3	1.75	2.3	
			Q1	1.3	1.75	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	Q2			± 100	nA
			Q1			± 100	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$	Q2			0.5	mA
			Q1			1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55^\circ C$	Q2			5	mA
			Q1			10	μA
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 15A$	Q2		2.3	3	m Ω
		$V_{GS} = 4.5V, I_D = 11A$	Q1		7.4	9.5	
		$V_{GS} = 10V, I_D = 20A$	Q2		1.9	2.4	
		$V_{GS} = 10V, I_D = 11A$	Q1		5.6	7	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$	Q2		70		S
		$V_{DS} = 5V, I_D = 11A$	Q1		50		

PK626HY

Dual N-Channel Enhancement Mode MOSFET

DYNAMIC									
Input Capacitance	C _{iss}		V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	Q2		3232		pF	
				Q1		824			
Output Capacitance	C _{oss}			Q2		606			
				Q1		162			
Reverse Transfer Capacitance	C _{rss}			Q2		353			
				Q1		103			
Gate Resistance	R _g		V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	Q2		1.25		Ω	
				Q1		2.3			
Total Gate Charge ²	Q _g	V _{GS} =10V	Q2 V _{DS} = 15V , V _{GS} = 10V,I _D = 20A Q1 V _{DS} = 15V , V _{GS} = 10V,I _D = 11A	Q2		63		nC	
				Q1		18			
				Q2		34			
				Q1		10			
Gate-Source Charge ²	Q _{gs}				Q2		8.3		
					Q1		2		
Gate-Drain Charge ²	Q _{gd}				Q2		15.5		
					Q1		6		
Turn-On Delay Time ²	t _{d(on)}		Q2 V _{DS} = 15V, I _D ≅ 20A, V _{GS} =10V, R _{GEN} = 6Ω Q1 V _{DS} = 15V , I _D ≅ 11A, V _{GS} = 10V, R _{GEN} =6Ω	Q2		31		nS	
					Q1		27		
Rise Time ²	t _r				Q2		15		
					Q1		20		
Turn-Off Delay Time ²	t _{d(off)}				Q2		64		
					Q1		40		
Fall Time ²	t _f				Q2		22		
					Q1		19		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _j = 25 °C)									
Continuous Current ³	I _S			Q2			71	A	
				Q1			20		
Forward Voltage ¹	V _{SD}		I _F = 1A, V _{GS} = 0V	Q2			0.6	V	
			I _F = 11A, V _{GS} = 0V	Q1			1.2		
Reverse Recovery Time	t _{rr}		Q2 I _F = 20A, dl _F /dt = 100A /μS	Q2		28.8		nS	
				Q1		16.5			
Reverse Recovery Charge	Q _{rr}		Q1 I _F = 11A, dl _F /dt = 100A /μS	Q2		12.7		nC	
				Q1		5.2			

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

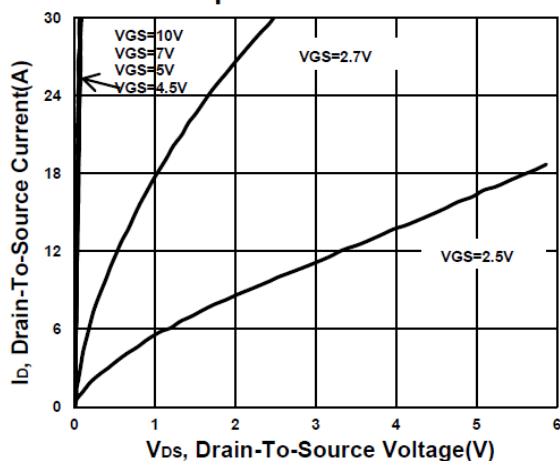
³Package limitation current : Q1=29A, Q2=34A.

PK626HY

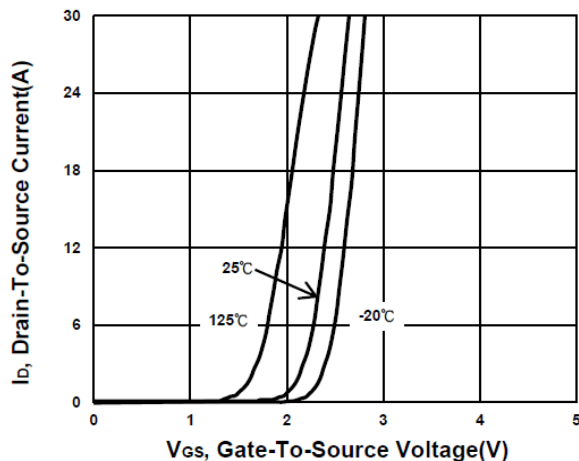
Dual N-Channel Enhancement Mode MOSFET

Q2

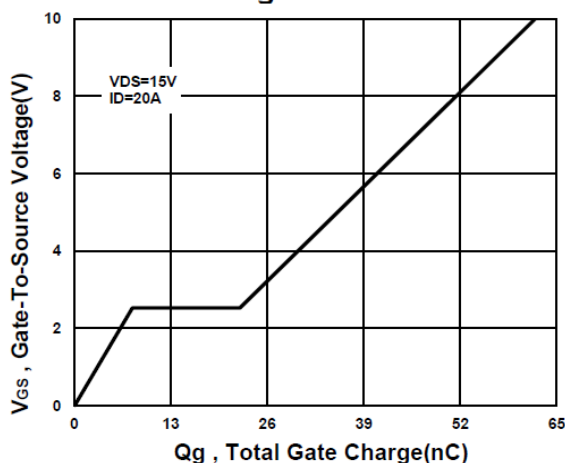
Output Characteristics



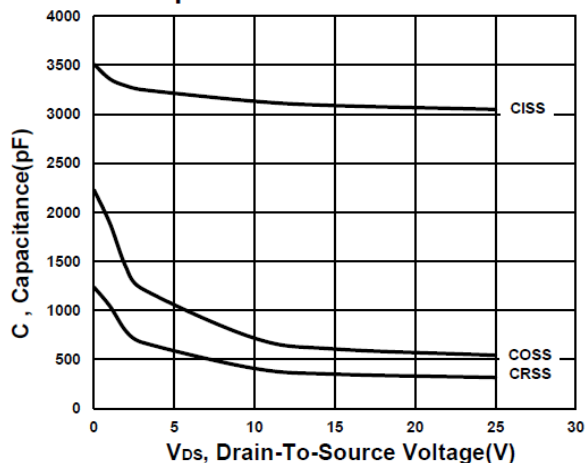
Transfer Characteristics



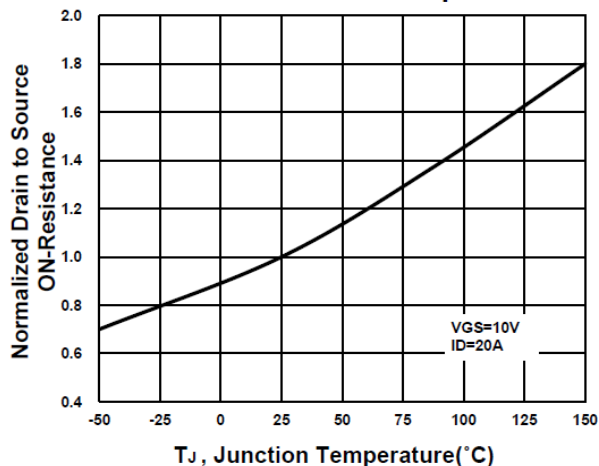
Gate charge Characteristics



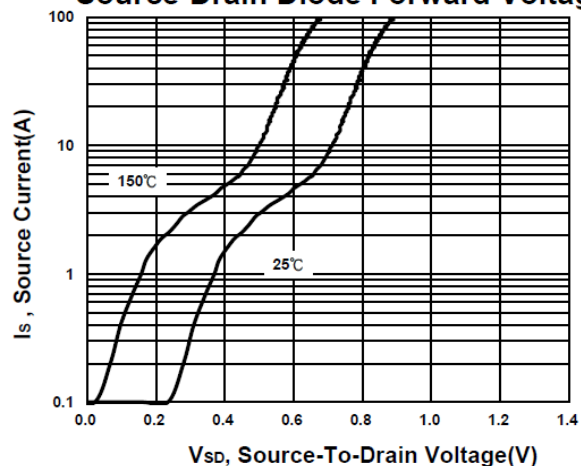
Capacitance Characteristic



On-Resistance VS Temperature



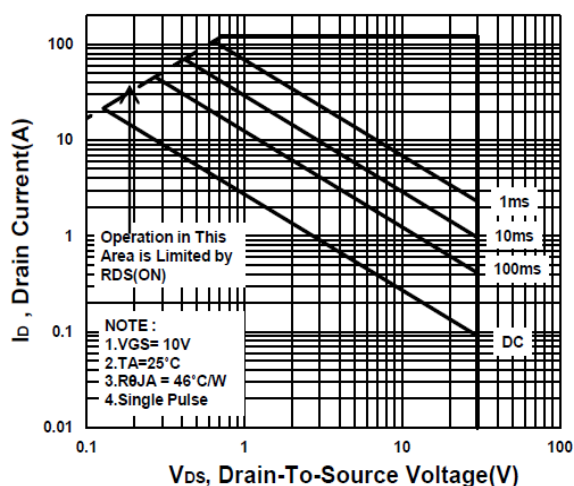
Source-Drain Diode Forward Voltage



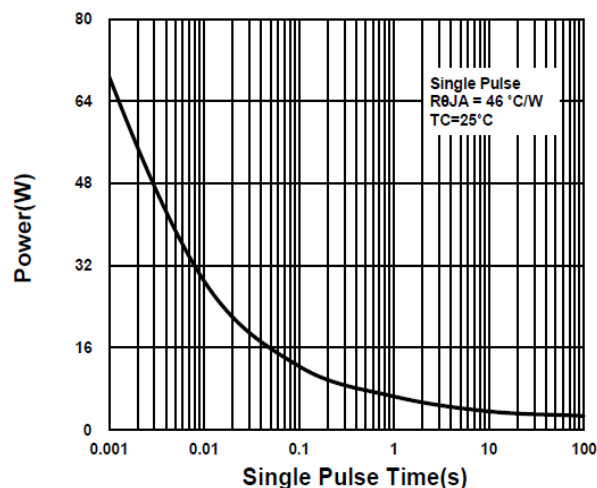
PK626HY

Dual N-Channel Enhancement Mode MOSFET

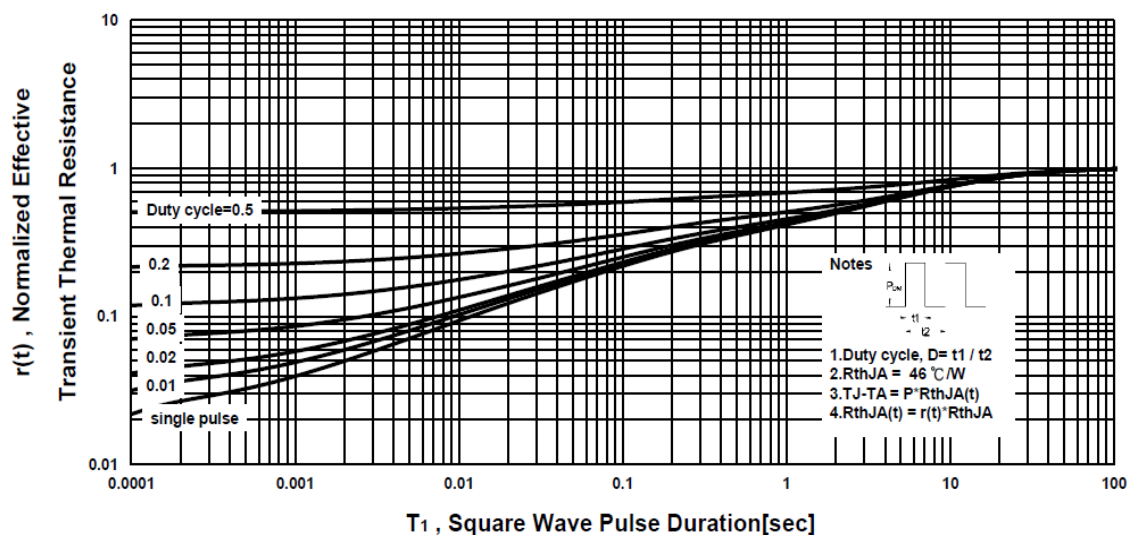
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

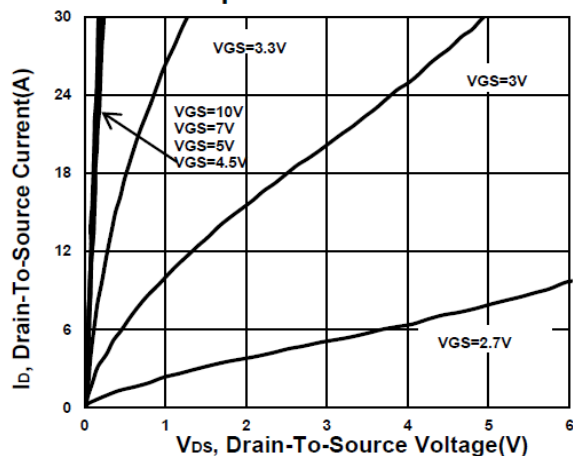


PK626HY

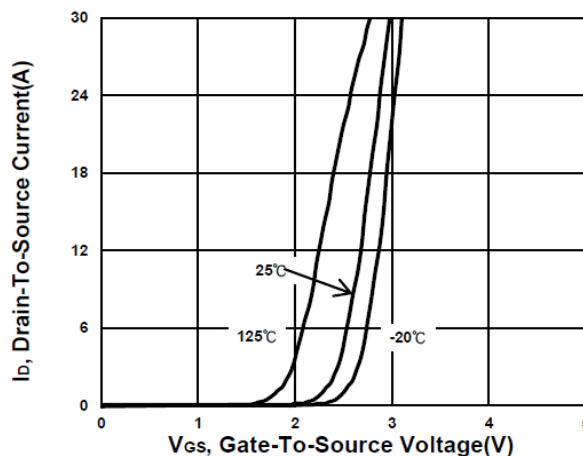
Dual N-Channel Enhancement Mode MOSFET

Q1

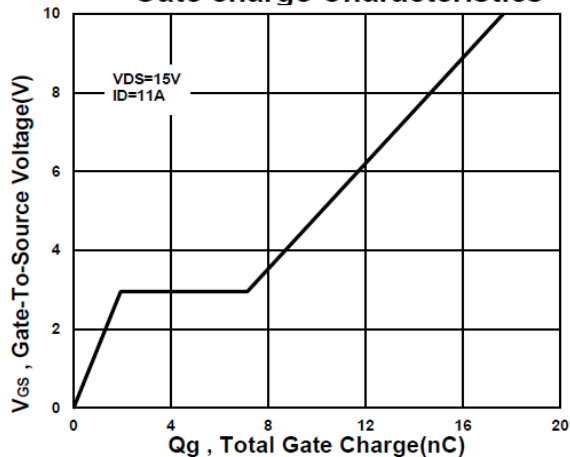
Output Characteristics



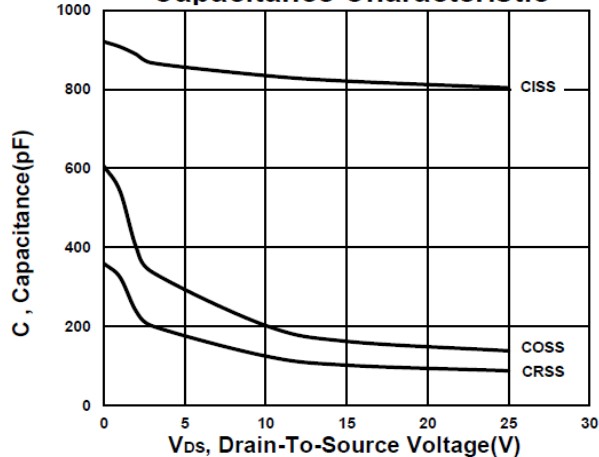
Transfer Characteristics



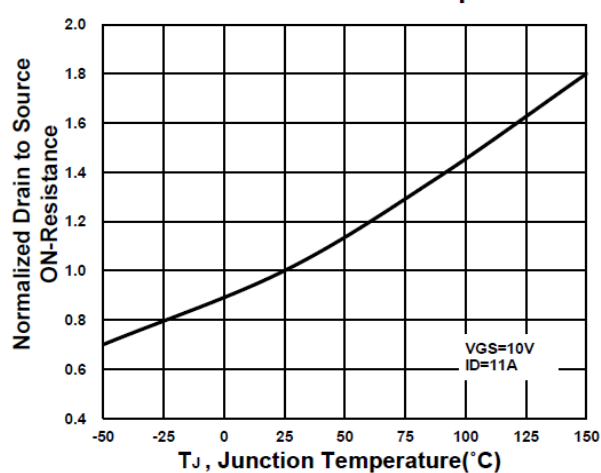
Gate charge Characteristics



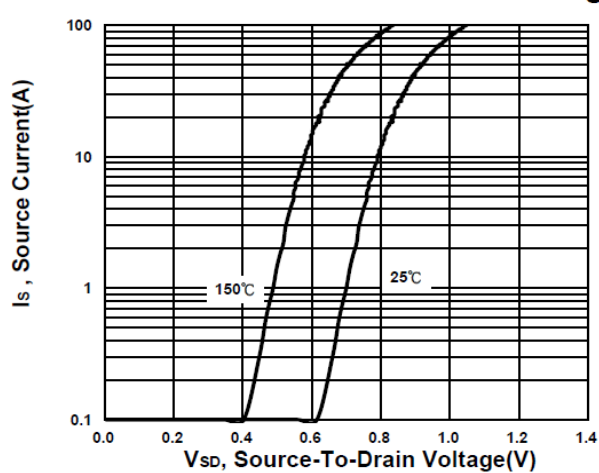
Capacitance Characteristic



On-Resistance VS Temperature



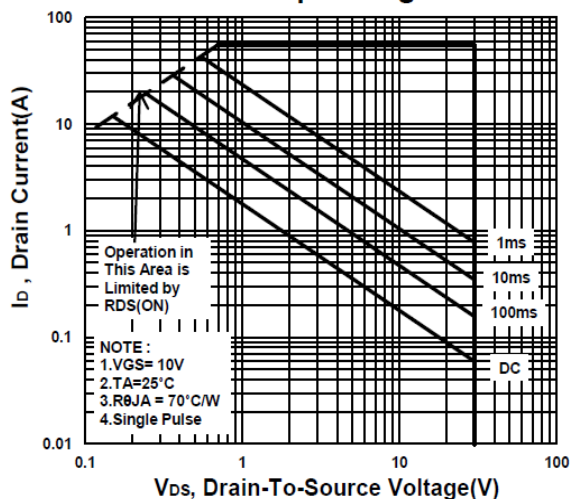
Source-Drain Diode Forward Voltage



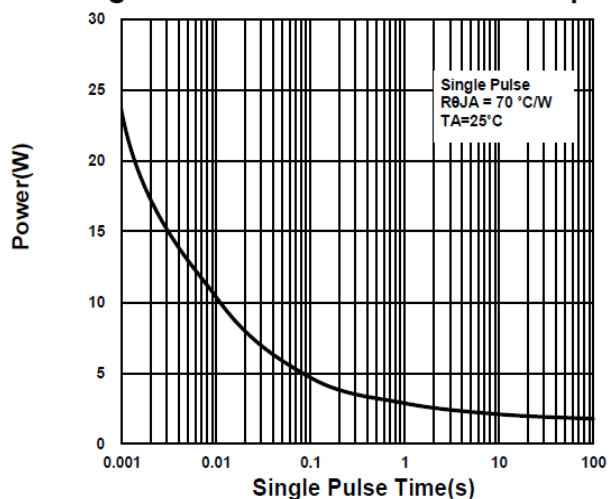
PK626HY

Dual N-Channel Enhancement Mode MOSFET

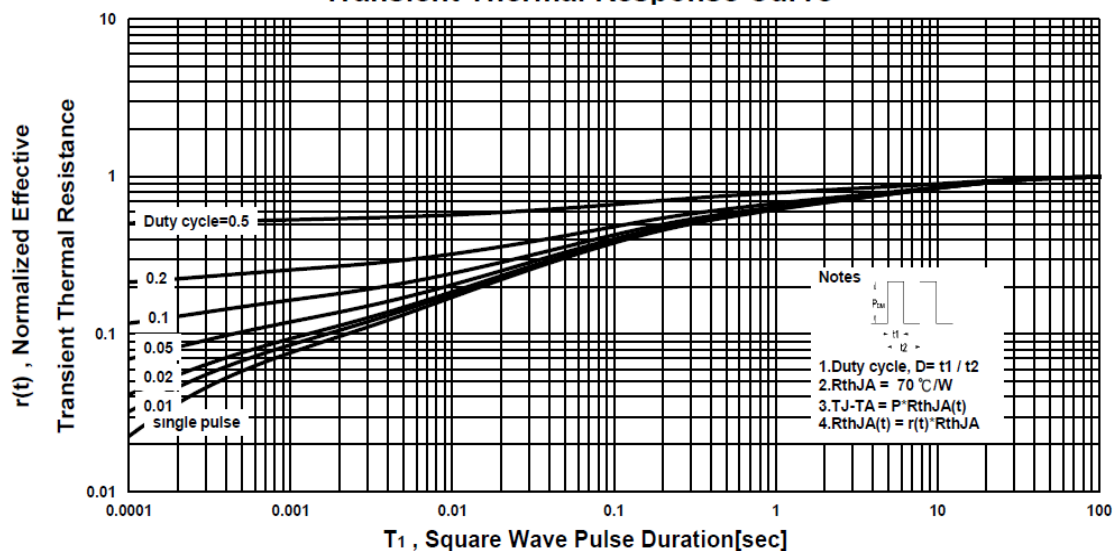
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



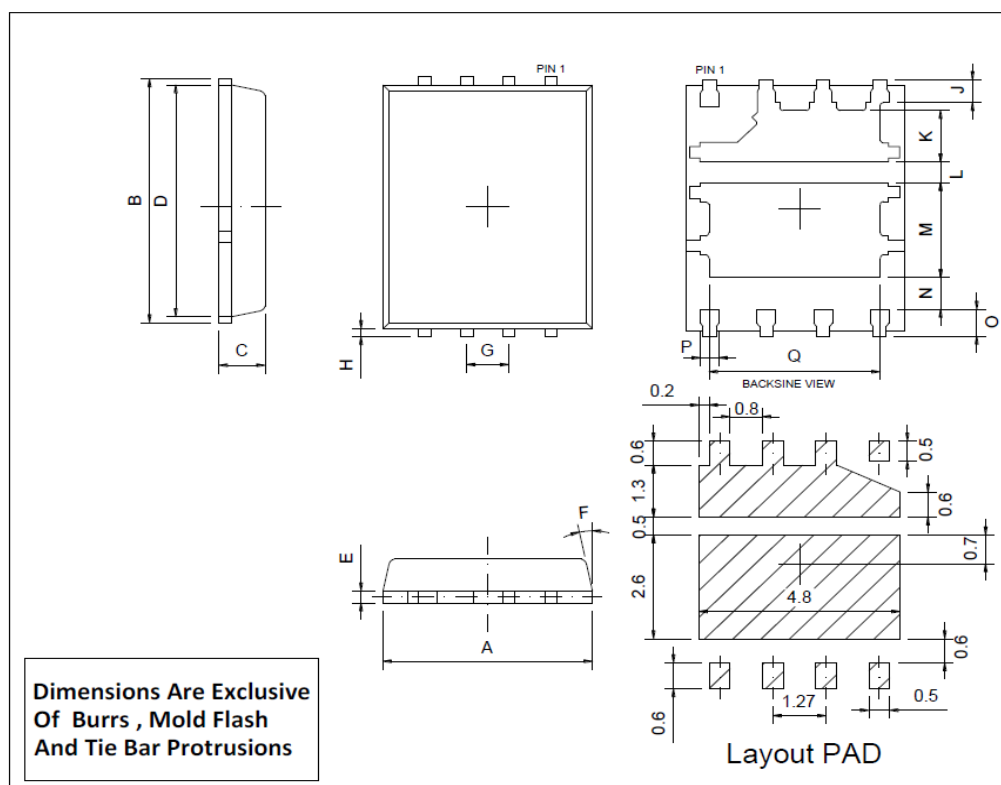
PK626HY

Dual N-Channel Enhancement Mode MOSFET

Package Dimension

PDFN 5x6P(上下 Dual) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	5	5.4	K	0.82	1.06	1.3
B	5.9	6.15	6.35	L	0.4	0.5	0.6
C	0.9	1	1.18	M	2.0	2.21	2.42
D	5.42	5.59	5.85	N	0.5	1	
E	0.15	0.25	0.35	O	0.42	0.56	0.71
F	0°	6°	12°	P	0.3	0.4	0.51
G	1.17	1.27	1.37	Q	3.61	4.05	4.5
H	0.06	0.21	0.36				
J	0.41	0.55	0.7				

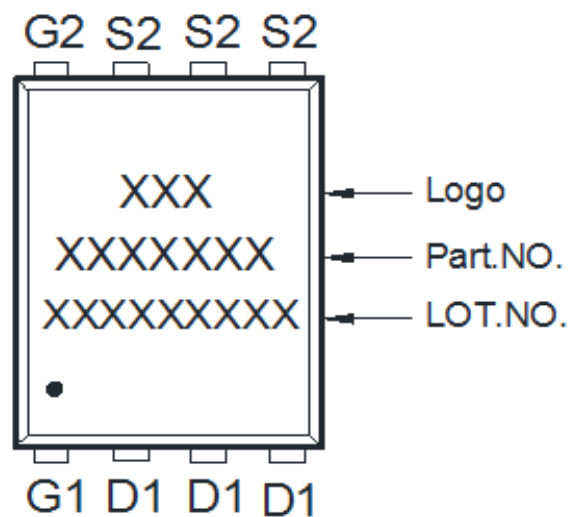


* 散热片形状会因为封装厂框架不同而有所差异。

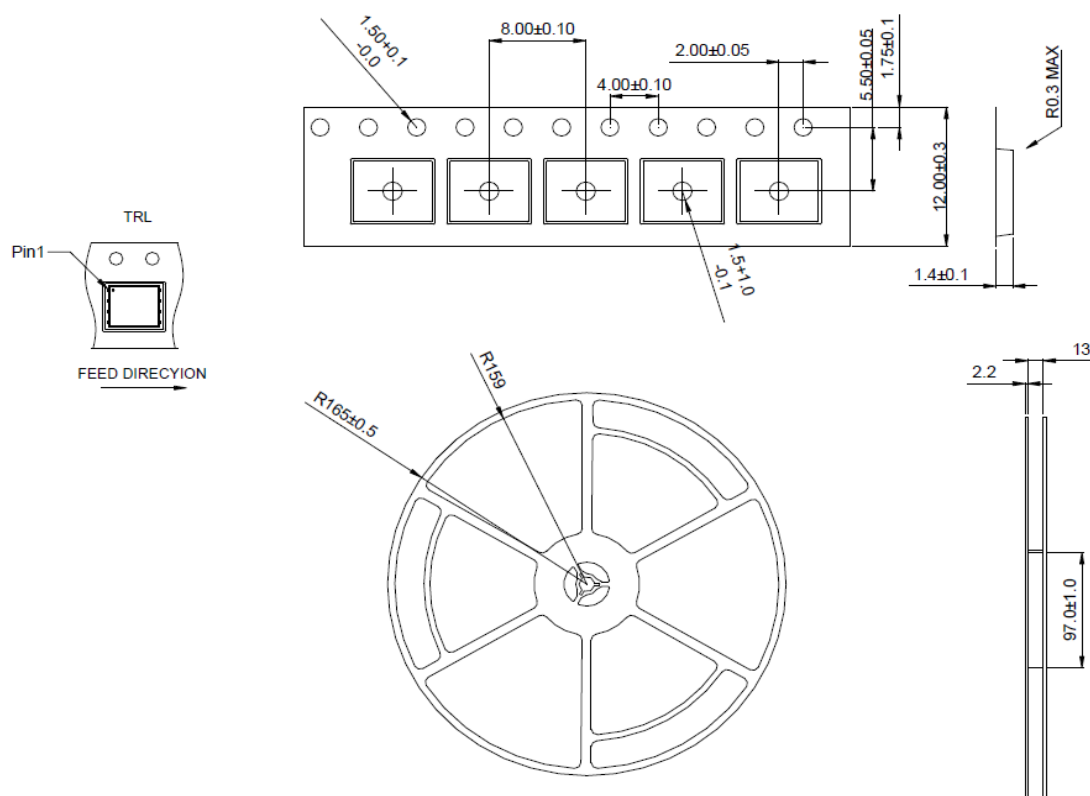
PK626HY

Dual N-Channel Enhancement Mode MOSFET

A. Marking Information



B. Tape&Reel Information:3000pcs/Reel

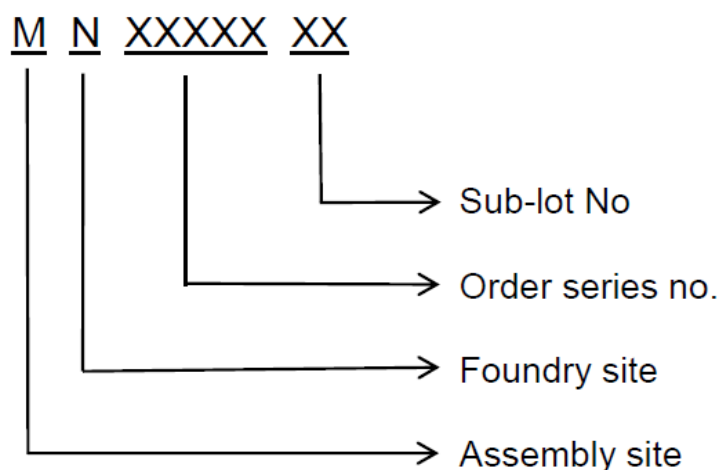


PK626HY

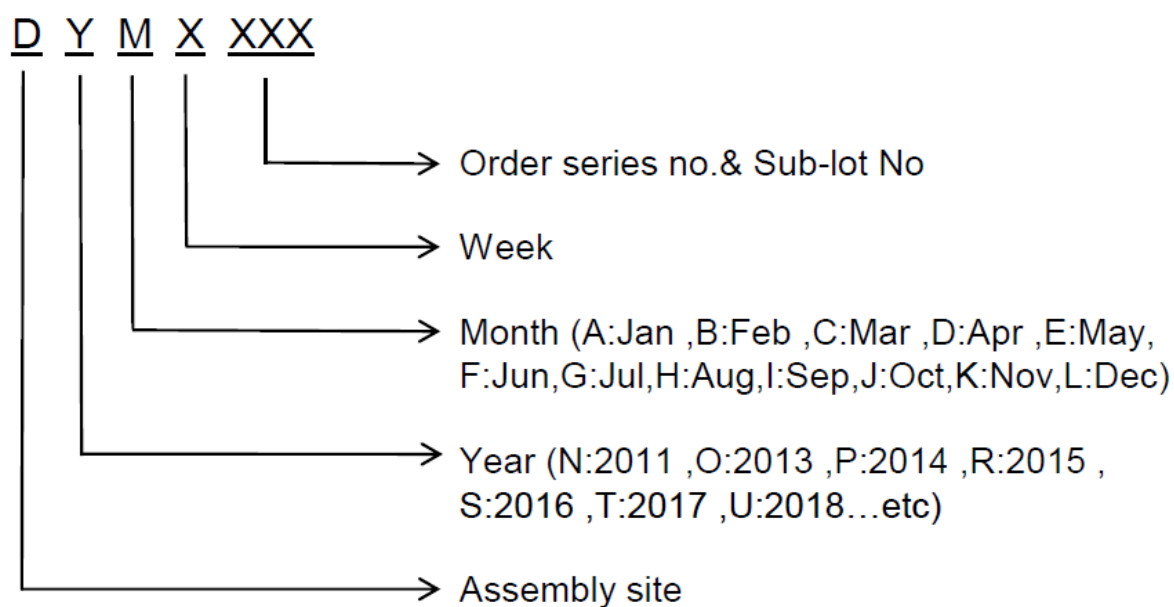
Dual N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1.Lot No.



2.Date Code



PK626HY

Dual N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G"和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert " / " between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least